



Product Content Sheet

Package family	TSSOP	Picture of typical product, optional
Date	28/Sep/2006	
Version	RoHS	

Composition part	Material group	Materials	CAS if applicable	Average mass [weight-%] *)	Sum [%]	Traces
Chip	Silicon and inorganic compounds	Si	7440-21-3	100	2.462017	-
Wires	Nobel Metal	Gold	7440-57-5	99.99	0.216128	-
Leadframe	Alloy	Copper	7440-50-8	95.256483	32.303207	-
		Silicon	7440-21-3	0.643625	0.218265	-
		Nickel	7440-02-0	2.970576	1.007376	-
		Magnesium	7439-95-4	0.148529	0.050369	-
		Silver	7440-22-4	0.980787	0.332603	-
Mold compound	Silica and thermoset epoxy resin	Si fused	60676-86-0	86.91	49.526519	-
		Epoxy & Phenol resin	Confidential	12.78	7.282809	-
		Carbon Black	1333-86-4	0.31	0.176657	-
DA Epoxy	Epoxy	Silver	7440-22-4	75	2.757008	-
		Epoxy Resin	Confidential	10	0.367601	-
		Gamma Butyrolactone	96-48-0	5	0.183801	-
		Amine	Confidential	5	0.183801	-
		Metal Oxide	Confidential	5	0.183801	-
Leadfinish	Metal Alloy	Sn	7440-31-5	100	2.748041	-
Marking	Laser	Laser	-	-	-	-
Sum in total:					100	-

Weight range	0.108732 g
Fluctuation margin	~10%

or:

Case sizes**) and weight range

-

*) related to package weight; weight in particular, see corresponding *package weight list*

**) optional

Not part of package family

Company	Texas Instruments Norway	Important remarks: 1) Traces are product parts, substances etc. that are below a percentage of 0.1 % by weight. Higher limits are accepted if the substance or material is legally regulated (see note no. 2). A list of the (legal) "... restrictions on substances ..." or materials is available at internet address: http://www.eicta.org/Content/Default.asp?PageID=113 . 2)
Address	Gaustadalleen 21, 0349 Oslo, Norway	
Support	http://www-k.ext.ti.com/sc/technical-support/pic/euro.htm	
Internet	www.ti.com	

- | | |
|----|---|
| 3) | Substances, materials etc. with possible harmful effects on human beings and the environment are listed. |
| 4) | There are no risks for human beings and to the environment if products are properly used as designated.
This shall not apply to risks caused during procedures for disposal etc. |
| 5) | All statements herein are based on our present knowledge.
If our products are used properly, there are no risks to human beings and/or the environment. |



Package Weight List

(Single weights of Products, materials data see **Product Content Sheet** on previous page)

Package family	TSSOP
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Uspec short*)	Package family*)	Package	Internal package code	Pin count	Weight [grams]	Remark
		7.8x4.4x0.9 TSSOP	TSSOP 24	24	0.108732 g	Device: CC1050

*) USpec short name and Package family are optional, e.g. for summary of several package weight lists

Company	Texas Instruments Norway
Address	Gaustadalleen 21, 0349 Oslo, Norway
Support	http://www-k.ext.ti.com/sc/technical-support/pic/euro.htm
Internet	www.ti.com

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